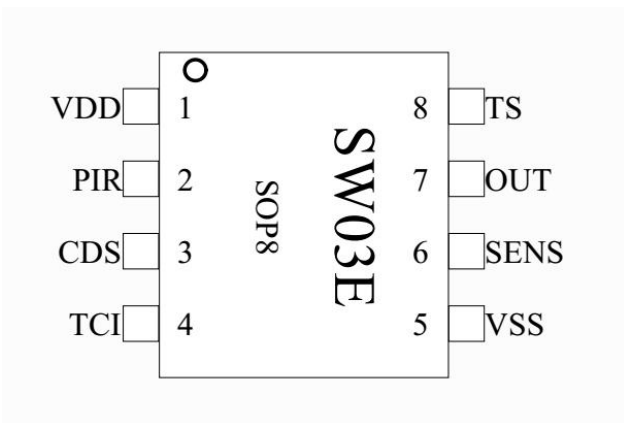
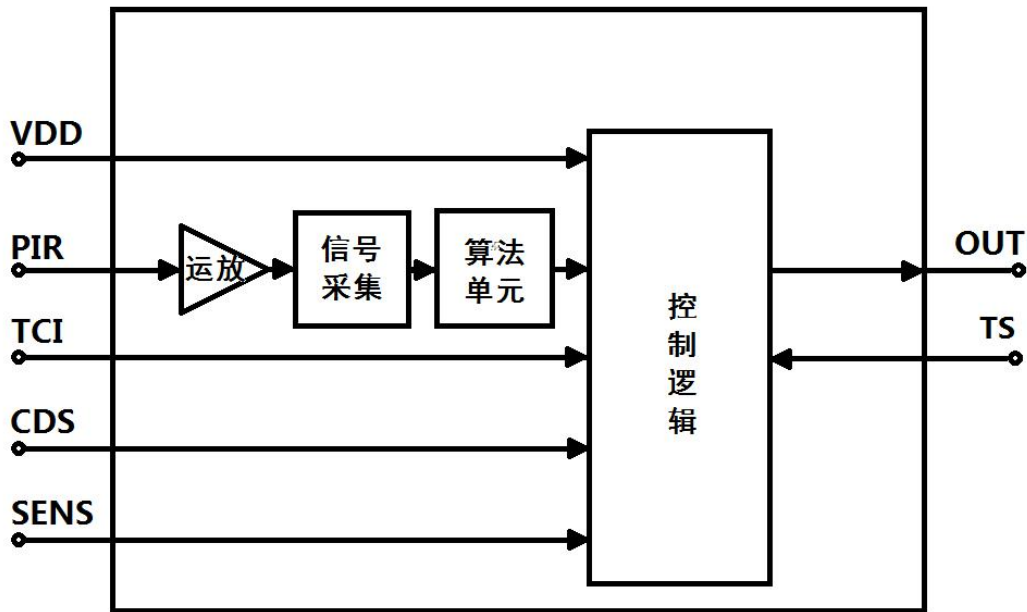


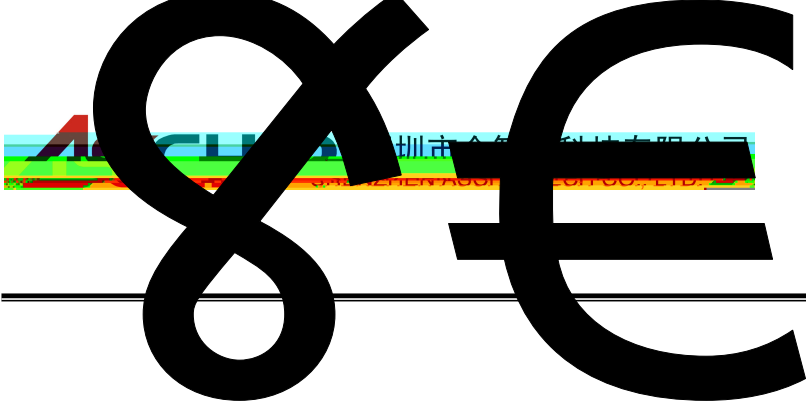
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CLIP 深圳市全智芯科技有限公司
SHENZHEN AQCHIP TECHNOLOGY CO., LTD.

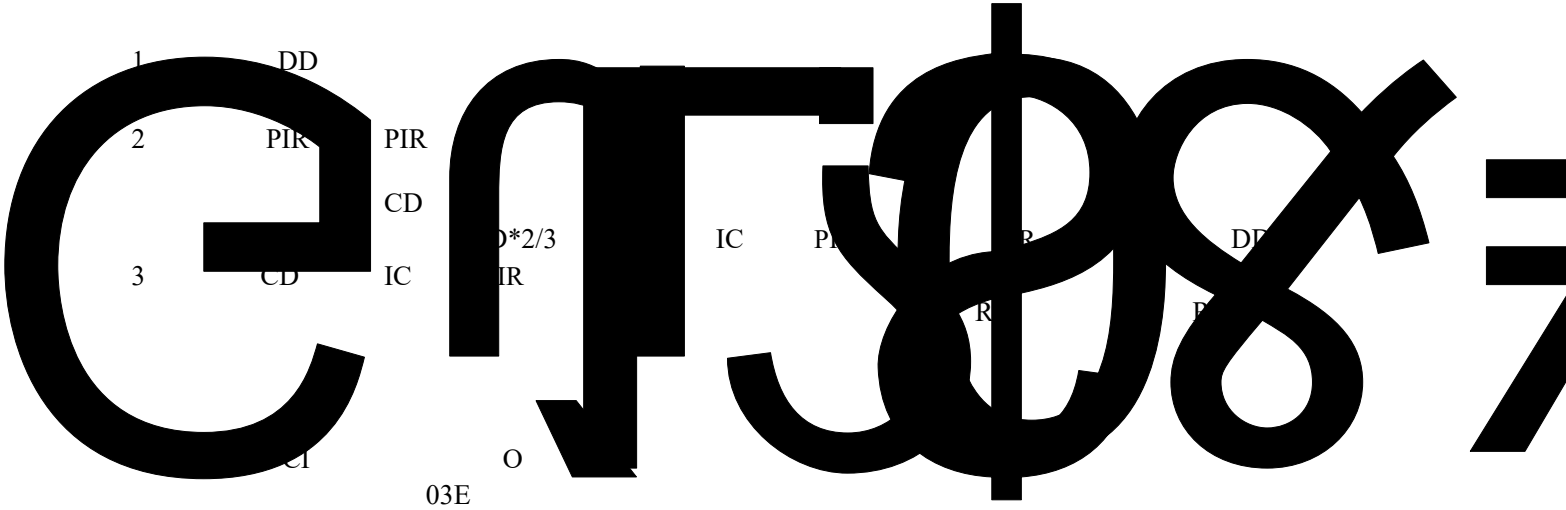
PIR

03E CMO PIR P I -R
M -
03E PIR





PIR



1

DD

2

PIR

PIR

CD

3

CD

IC

D*2/3

IC

PI

P

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CI

O

03E

5

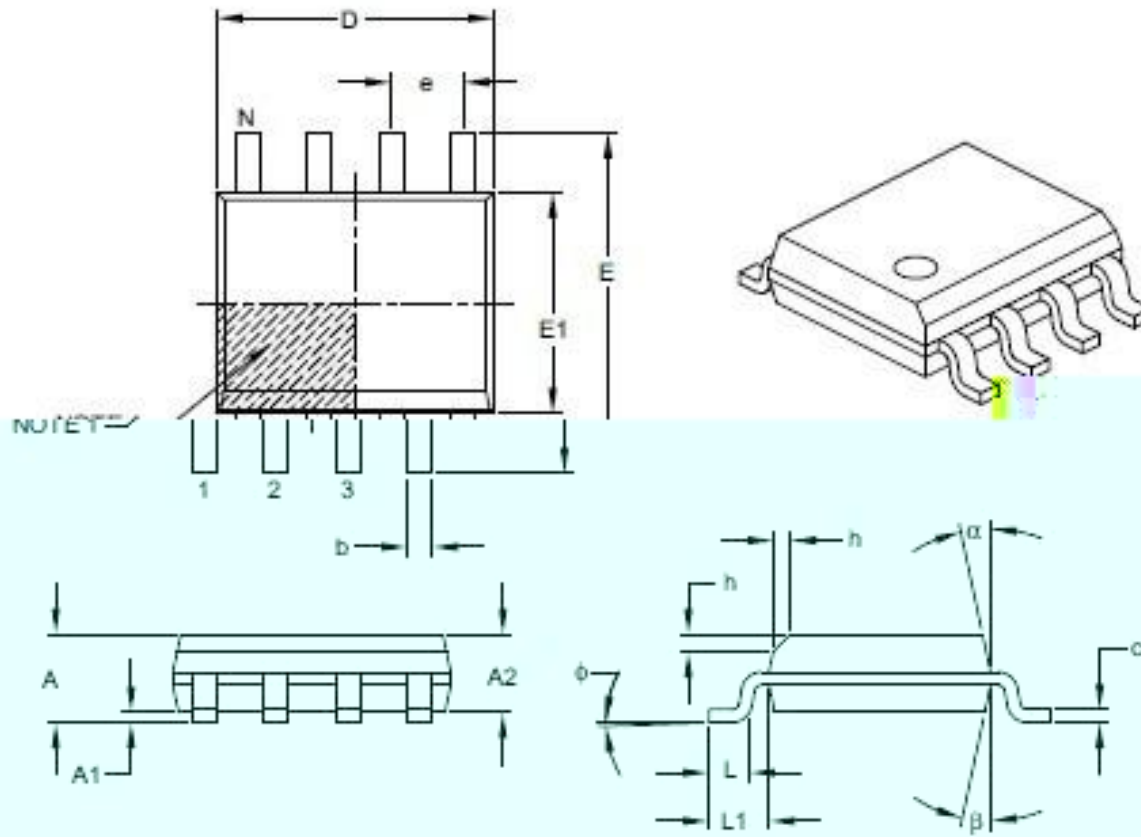
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EN

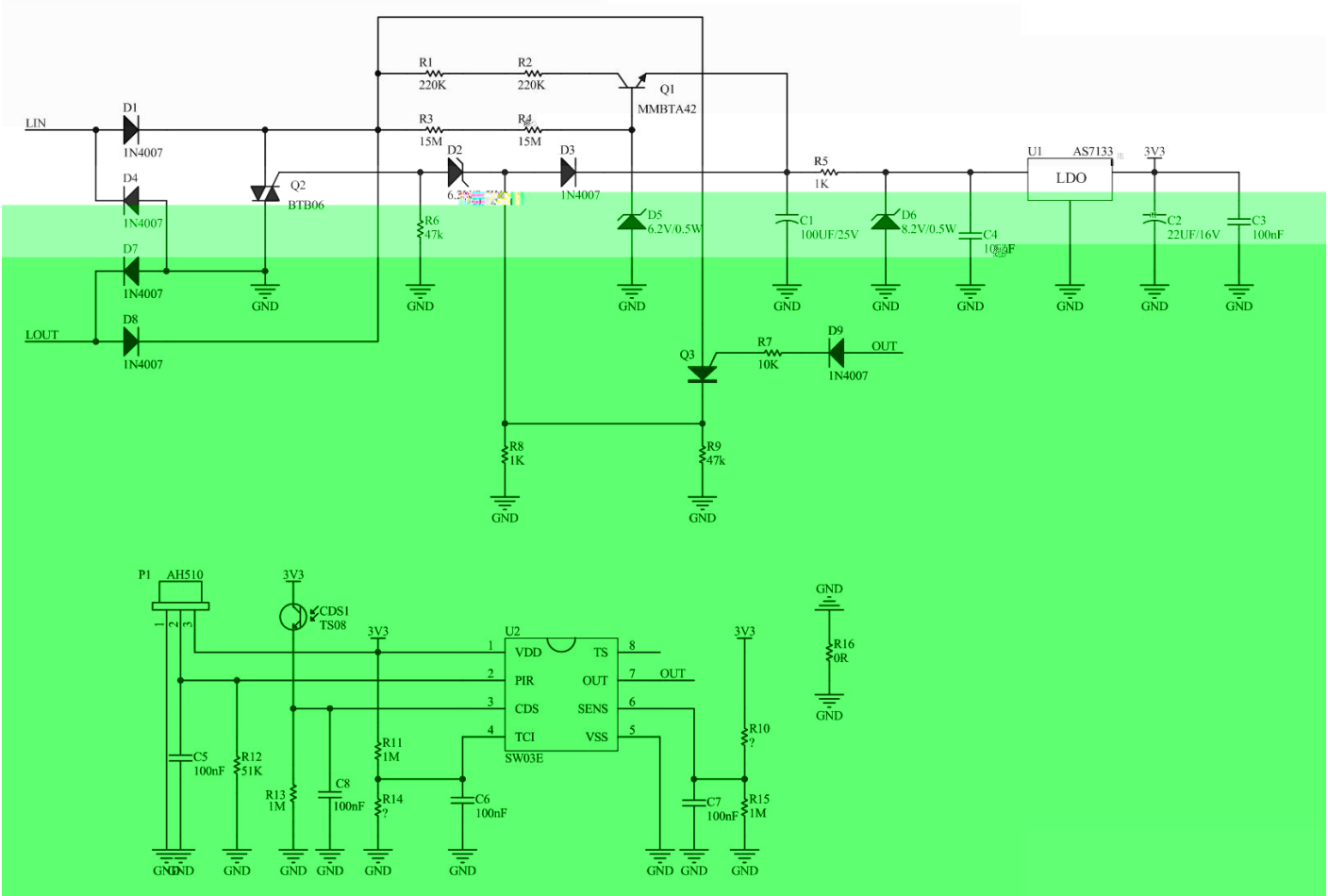
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3.3

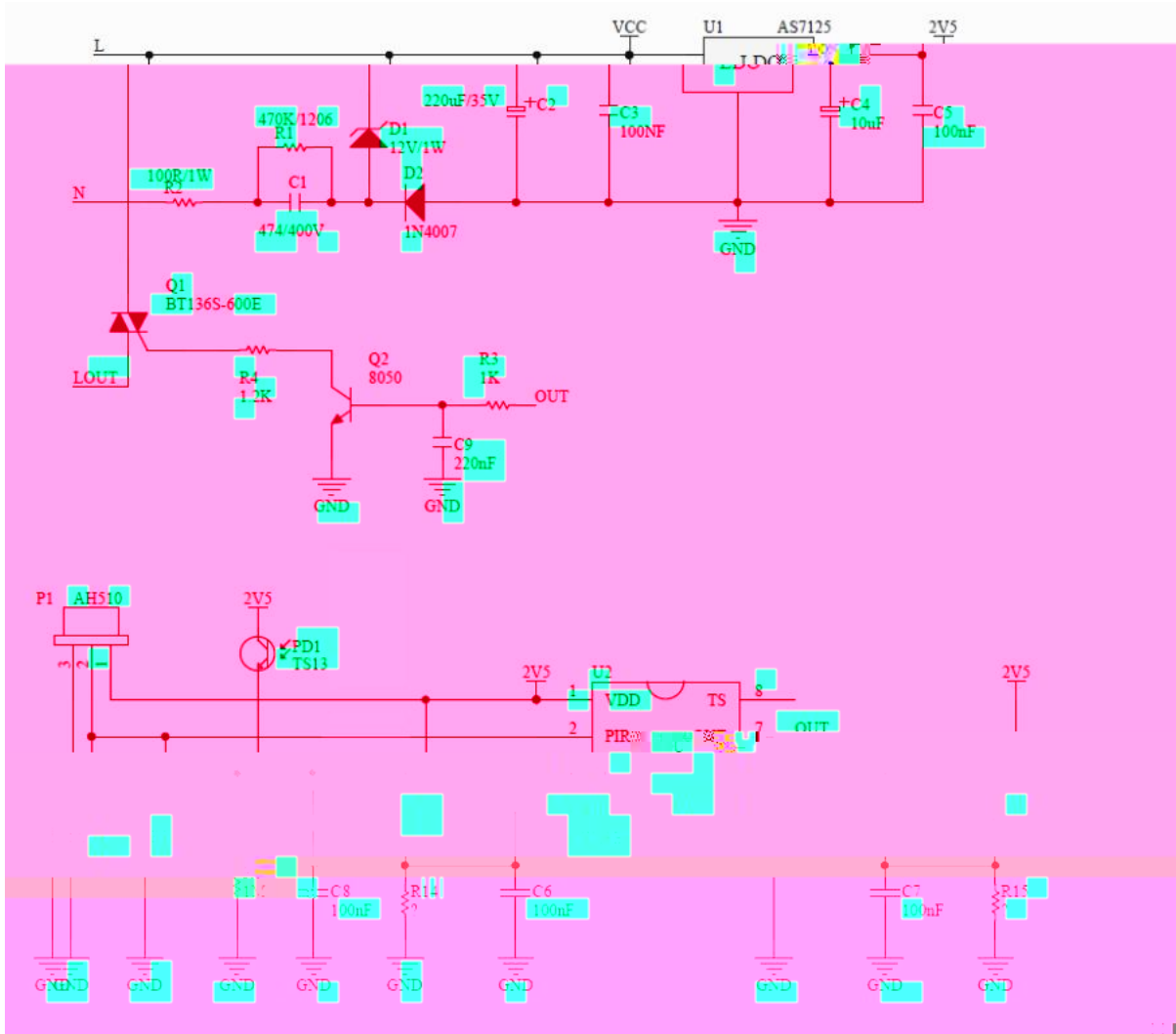
-



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		1.27 BSC		
Overall Height	A		-	1.00	1.75
Molded Package Thickness	A2		1.25	-	-
Standoff ϕ	A1		0.10	-	0.25
Overall Width	E		6.00 BSC		
Molded Package Width	E1		3.90 BSC		
Overall Length	D		4.90 BSC		
Chamfer (optional)	h		0.25	-	0.50
Foot Length	L		0.40	-	1.27
Footprint	L1		1.04 REF		
Foot Angle	ϕ		0°	-	8°
Lead Thickness	c		0.17	-	0.25
Lead Width	b		0.31	-	0.51
Mold Draft Angle Top	α		5°	-	15°
Mold Draft Angle Bottom	β		5°	-	15°



R14	
2M	1
1M	5
910K	10
820K	15
750K	20
680K	30
560K	45
470K	60
390K	90
300K	120
200K	180
100K	300
0	480



1 PIR EN ER 03E

2 PCB

3

4